



#### **DUAL N-CHANNEL ENHANCEMENT MODE MOSFET**

### **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>A</sub> = +25°C
60V	$3.0\Omega$ @ V <sub>GS</sub> = 10V	261mA
000	4.0Ω @ V <sub>GS</sub> = 4.5V	226mA

### **Description and Applications**

This MOSFET is designed to minimize the on-state resistance (RDS(ON)) yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Motor Control
- Power Management Functions

### **Features and Benefits**

- **Dual N-Channel MOSFET**
- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- **ESD Protected**
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

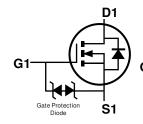
#### **Mechanical Data**

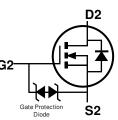
- Case: SOT363
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Alloy 42 Leadframe (Lead-Free Plating). Solderable per MIL-STD-202, Method 208 (3)
- Terminal Connections: See Diagram
- Weight: 0.006 grams (Approximate)

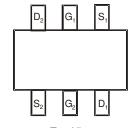




Top View







Top View Internal Schematic

November 2020

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### Ordering Information (Note 4)

Part Number	Case	Packaging
DMN62D4LDW-7	SOT363	3,000/Tape & Reel
DMN62D4LDW-13	SOT363	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and

**Equivalent Circuit** 

- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + CI) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

### **Marking Information**

# **SOT363** ΥM 2D4 5Dt

2D4 = Product Type Marking Code  $\overline{Y}M$  = Date Code Marking  $\overline{Y}$  = Year (ex: H = 2020)

M = Month (ex: 9 = September)

Data Cada Kay

Date Code Key												
Year	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031
Code	Н		J	K	L	М	N	0	Р	R	S	Т
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec



# **Maximum Ratings** (@ $T_A = +25^{\circ}C$ , unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Drain-Source Voltage	V <sub>DSS</sub>	60	V		
Gate-Source Voltage			$V_{GSS}$	±20	V
Continuous Drain Current (Note 6) Vgs = 10V	lo	261 208	mA		
Maximum Continuous Body Diode Forward Current	t (Note 6)	ls	261	mA	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%	I <sub>DM</sub>	1.1	Α		
Pulsed Source Current (10µs Pulse, Duty Cycle = 1	1%)		Ism	1.1	Α

### Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

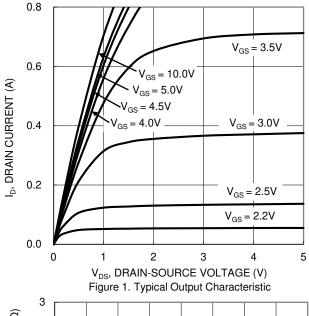
Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		$P_{D}$	0.33	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	Reja	379	°C/W
Total Power Dissipation (Note 6)		PD	0.45	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	R <sub>0JA</sub>	278	°C/W
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C

## Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)		l .		I.	I.	,
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	60	_	_	V	$V_{GS} = 0V, I_{D} = 250\mu A$
Zero Gate Voltage Drain Current	IDSS	_	_	1	μΑ	V <sub>DS</sub> = 60V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±10	μΑ	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)	•					
Gate Threshold Voltage	V <sub>GS(TH)</sub>	1.0	_	2.0	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$
Static Drain-Source On-Resistance	RDS(ON)	-	1.3 1.5	3.0 4.0	Ω	$V_{GS} = 10V, I_{D} = 200mA$ $V_{GS} = 4.5V, I_{D} = 150mA$
Diode Forward Voltage	V <sub>SD</sub>	_	0.8	1.4	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = 115mA
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	Ciss	_	41	_	pF	.,
Output Capacitance	Coss	l	4.5	_	pF	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V f = 1.0MHz
Reverse Transfer Capacitance	Crss	_	2.7	_	pF	1 - 1.000112
Gate Resistance	Rg	l	224	_	Ω	$f = 1MHz$ , $V_{GS} = 0V$ , $V_{DS} = 0V$
Total Gate Charge (V <sub>GS</sub> = 4.5V)	$Q_g$	_	0.51	_	nC	
Total Gate Charge (VGS = 10V)	Qg	l	1.04	_	nC	$V_{DS} = 15V$ ,
Gate-Source Charge	Qgs	l	0.16	_	nC	$I_D = 200 \text{mA}$
Gate-Drain Charge	Qgd	_	0.18	_	nC	
Turn-On Delay Time	t <sub>D(ON)</sub>	_	6.9	_	ns	
Turn-On Rise Time	tR	_	5.8	_	ns	$V_{DD} = 30V, V_{GS} = 10V,$
Turn-Off Delay Time	tD(OFF)	_	37.8	_	ns	$R_G = 150\Omega$ , $I_D = 200mA$
Turn-Off Fall Time	tF	_	14.3	_	ns	
Reverse Recovery Time	t <sub>RR</sub>	_	88	_	ns	I <sub>F</sub> = 1A, di/dt = 100A/μs
Reverse Recovery Charge	Qrr	_	29	_	nC	I <sub>F</sub> = 1A, di/dt = 100A/μs

 Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
Short duration pulse test used to minimize self-heating effect.
Guaranteed by design. Not subject to product testing. Notes:





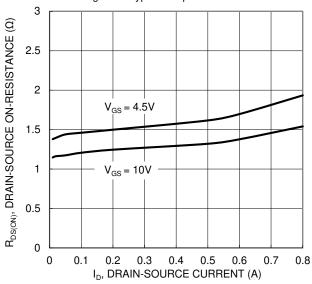


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

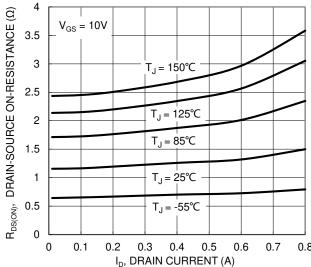
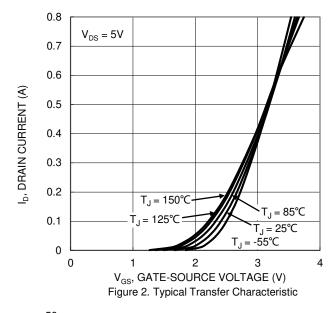
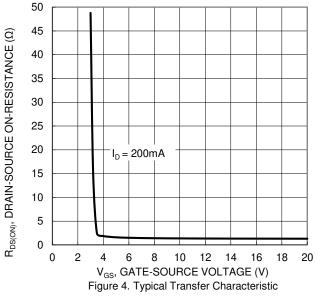


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature





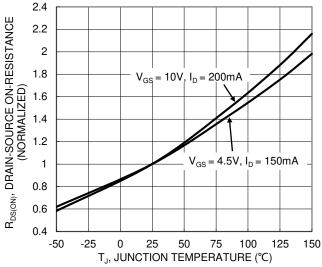


Figure 6. On-Resistance Variation with Junction Temperature





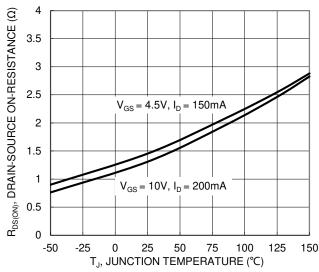
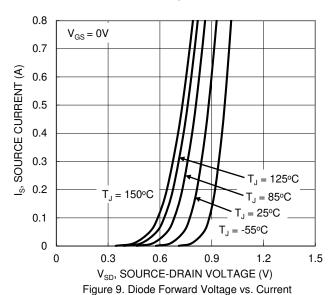
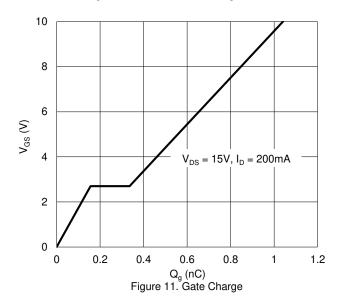
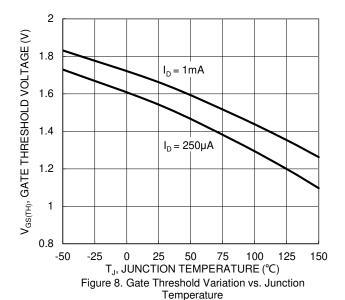
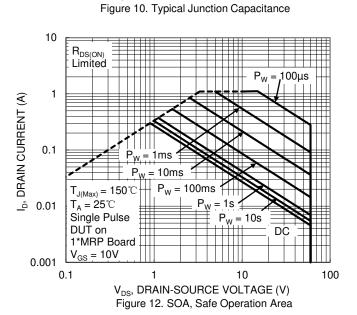


Figure 7. On-Resistance Variation with Junction Temperature











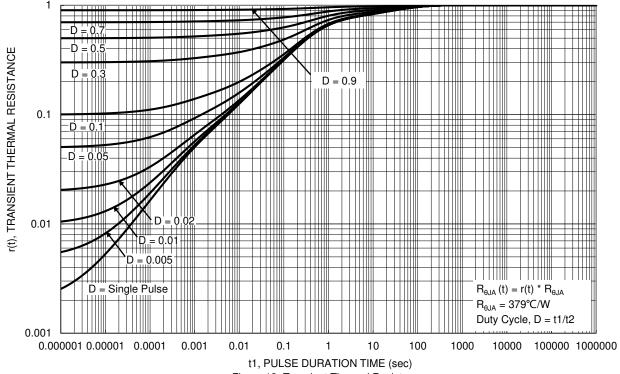


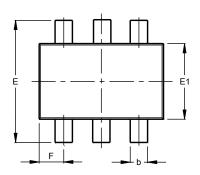
Figure 13. Transient Thermal Resistance

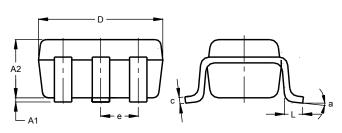


# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.





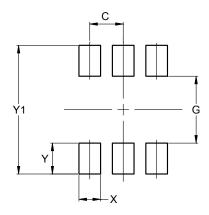


SOT363							
Dim	Min	Max	Тур				
A1	0.00	0.10	0.05				
A2	0.90	1.00	0.95				
b	0.10	0.30	0.25				
C	0.10	0.22	0.11				
D	1.80	2.20	2.15				
Е	2.00	2.20	2.10				
E1	1.15	1.35	1.30				
е	C	.650 E	BSC				
F	0.40	0.45	0.425				
L	0.25	0.40	0.30				
а	0°	8°					
All Dimensions in mm							

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### SOT363



Dimensions	Value (in mm)
C	0.650
G	1.300
X	0.420
Υ	0.600
Y1	2.500



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